

ABSTRACT OF THE DISCLOSURE

Systems and methods for plating printed circuit boards. Traces are formed using internal and external layers of a printed circuit board from conductive paths including contact pads to a side edge of the printed circuit board. The traces are connected with a plating bar to form a single conductive path that permits all conductive paths to be plated at the same time. When the plating bar is removed, the traces are severed to electrically isolate the various conductive paths. Traces are not present at a front edge of the printed circuit board by the contact pads. A small hole is drilled through traces used to plate transmission lines such that the traces do not affect the transmission characteristics of the transmission lines.

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